

推荐焊接条件

RECOMMEND SOLDERING CONDITIONS

型号 Part number	焊接条件 Soldering conditions
CSA20 CSA30 CSA70 CDA70	<p>推荐温度曲线 Recommended Temperature Profile</p> <p>流体焊接 Flow soldering conditions 共晶焊接时 Eutectic Solder</p> <p>1) 保持时间为元件表面温度达到上述温度后起算的时间。 2) ΔT应在100°C以内。 3) 焊接后切勿迅速冷却，而应缓慢冷却。</p> <p>1) Time shown in the above figures is measured from the point when chip surface reaches temperature. 2) Temperature difference in high temperature part should be within 100°C. 3) After soldering, do not force cool, allow the parts to cool gradually.</p> <p>无铅焊接时 Lead free Solder</p> <p>1) 保持时间为元件表面温度达到上述温度后起算的时间。 2) ΔT应在110°C以内。 3) 焊接后切勿迅速冷却，而应缓慢冷却。</p> <p>1) Time shown in the above figures is measured from the point when chip surface reaches temperature. 2) Temperature difference in high temperature part should be within 110°C. 3) After soldering, do not force cool, allow the parts to cool gradually.</p>
TH03 TX03 TN05 TC05 TH05 TD05 TX05 TZ05 TN11 TH11 TD11 TN10 TC10 TN20 TC20 TH20 MN18 MH18 GA13 GA20 GH13 GH20	<p>回流焊接 Reflow soldering conditions 共晶焊接时 Eutectic Solder</p> <p>1) 保持时间为元件表面温度达到上述温度后起算的时间。 2) ΔT应在100°C以内。 3) 焊接后切勿迅速冷却，而应缓慢冷却。</p> <p>1) Time shown in the above figures is measured from the point when chip surface reaches temperature. 2) Temperature difference in high temperature part should be within 100°C. 3) After soldering, do not force cool, allow the parts to cool gradually.</p> <p>无铅焊接时 Lead free Solder</p> <p>1) 保持时间为元件表面温度达到上述温度后起算的时间。 2) ΔT应在110°C以内。 3) 焊接后切勿迅速冷却，而应缓慢冷却。</p> <p>1) Time shown in the above figures is measured from the point when chip surface reaches temperature. 2) Temperature difference in high temperature part should be within 110°C. 3) After soldering, do not force cool, allow the parts to cool gradually.</p> <p>※1 仅可进行回流焊接 ※2 仅为镀锡品或仅适用于流动焊接。 其它产品请在规格书所记载的条件下使用。</p> <p>※1 Reflow only ※2 Tin plated only, and flow only. Soldering method of the other products refer to the individual specification.</p>

【焊接时的一般注意事项】

- 若焊接温度过高、焊接时间过长，端子电极处可能会发生浸析，从而导致粘着力下降或性能劣化。
- 焊接时请参照上述温度曲线进行。
但超过200°C的温度应控制在50秒以内。
- 焊剂应使用低活性（Cl含有率在0.2wt%以下）的产品。如果焊剂为水溶性、且清洗不充分的话，可能会损伤元件下部的绝缘，应予以注意。

【清洗】

用超声波进行清洗时，输出过大会引起主板共振，振动可能会造成主板破裂或端子电极粘着力下降。故此，推荐按以下条件进行清洗。

频率：40kHz以下
输出：20W/l
清洗时间：5分钟以内

General attention to soldering

- High soldering temperatures and long soldering times can cause leaching of the termination, decrease in adherence strength, and the change of characteristic may occur.
- For soldering, please refer to the soldering curves above.
However, please keep exposure to temperatures exceeding 200°C to under 50 seconds.
- Please use a mild flux(containing less than 0.2wt% Cl). Also, if the flux is water soluble, be sure to wash thoroughly to remove any residue from the underside of components, that could affect resistance.

Cleaning

When using ultrasonic cleaning, the board may resonate if the output power is too high. Since this vibration can cause cracking or a decrease in the adherence of the termination, we recommend that you use the conditions below.

Frequency: 40kHz max.
Output power: 20W/liter
Cleaning time: 5minutes max.